

Material Content Data Sheet

Sales Product Name	TLE6250G	**Issued**	09. March 2021
MA#	MA000041099		
Package	P-DSO-8-3	**Weight***	80.97 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.700	4.57	4.57	45695	45695
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		115	
	non noble metal	zinc	7440-66-6	0.037	0.05		458	
	non noble metal	iron	7439-89-6	0.742	0.92		9159	
	non noble metal	copper	7440-50-8	30.114	37.19	38.17	371903	381635
wire	noble metal	gold	7440-57-5	0.172	0.21	0.21	2127	2127
encapsulation	organic material	carbon black	1333-86-4	0.219	0.27		2707	
	inorganic material	antimonytrioxide	1309-64-4	0.877	1.08		10828	
	plastics	brominated resin	-	0.877	1.08		10828	
	plastics	epoxy resin	-	5.041	6.23		62260	
	inorganic material	silicondioxide	60676-86-0	36.824	45.47	54.13	454764	541387
leadfinish	non noble metal	tin	7440-31-5	0.163	0.20		2010	
	non noble metal	lead	7439-92-1	0.256	0.32	0.52	3166	5176
plating	noble metal	silver	7440-22-4	0.541	0.67	0.67	6686	6686
glue	plastics	epoxy resin	-	0.420	0.52		5188	
	noble metal	silver	7440-22-4	0.980	1.21	1.73	12106	17294
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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